

#### Fast Recovery Bridge Rectifiers Reverse Voltage-1000v Forward current-10A

#### **Features**

Glass passivated chip
High surge current capability
Ldeal for surface mounted applications
Low power loss, high efficiency
Plastic Case Material has UL Flammability

#### Mechanical Data

Package:HBS

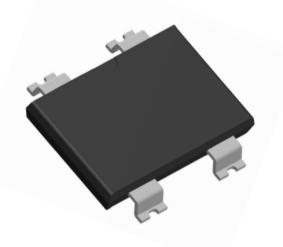
Terminals:Tin Plated leads, solderable per

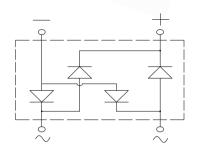
Mil-STD-750 Method 2026

Polarity: As marked

Molding compound meets UL 94 V-0 flammability rating,

**ROHS-compliant** 





#### Maximum Ratings (Ta=25 ℃ Unless otherwise specified)

Twaximam ratings (14 20 C offices otherwise sp	1 1			
Type Number	SYMBOL	RHBS1010	Umit	
Maximum Recurrent Peak Reverse Voltage	$V_{RRM}$	1000	V	
Maximum RMS Voltage	V <sub>RMS</sub>	700	V	
Maximum DC Blocking Voltage	V <sub>DC</sub>	1000	V	
Maximum Average Forward Rectified Current	IO <sub>(AV)</sub>	10.0	А	
Peak Forward Surge Current 8.3ms Single half-sine-wave superimposed on rated load(JEDEC Method) on rated	IFSM -	180.0	А	
Forward Surge Current (Non-repetitive) @1ms, square wave, 1 cycle, Tj=25 ℃	III OW	360.0	А	
Current squared time @1ms≤t8.3≤ms Tj=25℃,Rating of per diode	l <sup>2</sup> t	134.5	A <sup>2</sup> S	
Maximum Forward Voltage at 10.0A DC	V <sub>FM</sub>	1.3	V	
Maximum Reverse Current TA = 25℃	ID	5	uA	
at Rated DC Blocking Voltage TA = 125℃	⊢ IR ⊢	100		
Maximum reverse recovery time (IF=0.5A,IR=1.0A, Irr=0.25A)	Trr	500	ns	
Typical Thermal Resistance	R <sub>QJa</sub>	75.0	°C/W	
Operating Junction Temperature Range	T <sub>J</sub>	55to+150	$^{\circ}$	
Storage Temperature Range	T <sub>STG</sub>	55to+150	$^{\circ}$ C	

FIG. 1MAXIMUM AVERAGE FORWARD CURRENT DERATING

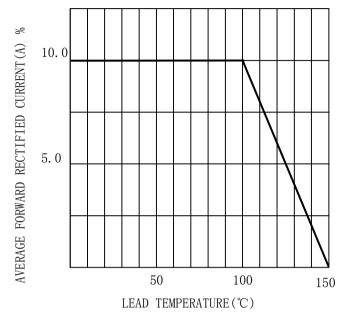


FIG. 2TYPICAL FORWARD CHARACTERISTICS

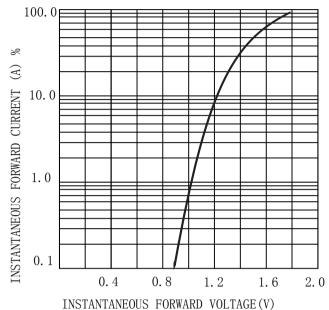


FIG. 3MAXIMUM NON-REPEITIVE SURGE CURRENT

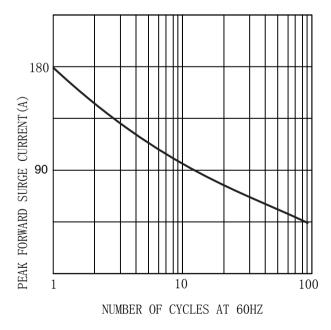
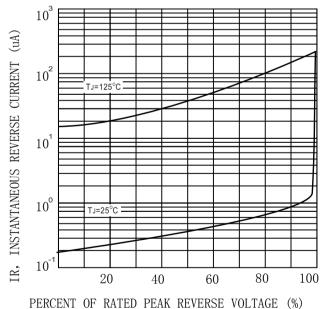
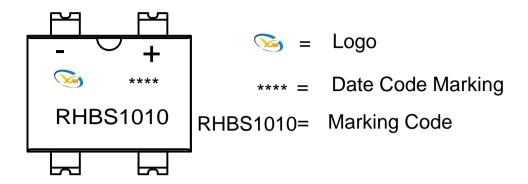


FIG. 4 TYPICAL REVERSE CHARACTERISTICS (per element)



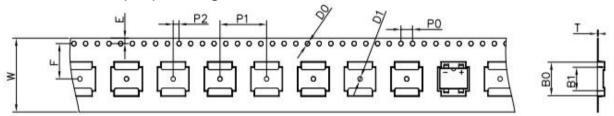
### **MARKING INFORMATION**

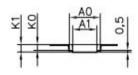


Print according to customer request

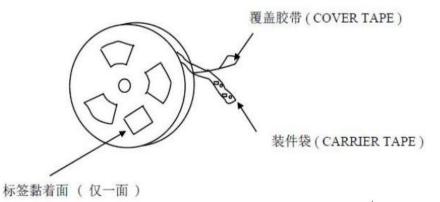
### **PACKING REQUIRMENTS**

· Carrier tape packing



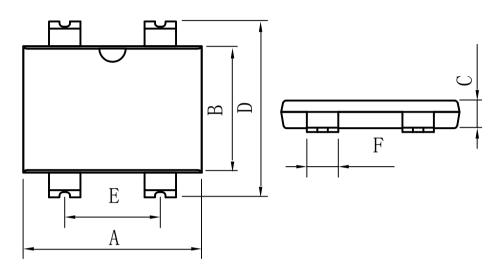


Specificati ons	Carrier tape type	Ao	A1	ВО	B1	КО	K1	Ро	W	t	Exiplain
HBS	DIM	10.6	8.3	10.9	7.6	1.9	2.4	4.0	16.0	0.3	
	TOLE	±0.2	±0.2	±0.2	±0.2	±0.1	±0.1	±0.1	±0.2	±0.05	



DEVICE TYPE	Units/Reel	Tubes/ Inner Box	Units/ Inner Box	Inner Box/ Carton Box	Units/ Carton Box	
HBS	1500	1	1500	10	15000	

### Outline Dimensions



HBS						
DIM	INC	HES	MM			
	MIN	MAX	MIN	MAX		
A	0. 39	0. 41	10.0	10. 4		
В	0. 28	0. 29	7. 0	7.4		
С	0.06	0. 07	1. 4	1. 7		
D	0.38	0.40	9. 7	10. 2		
Е	0. 21	0. 22	5. 3	5. 7		
F	0.07	0.08	1.7	2.0		



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